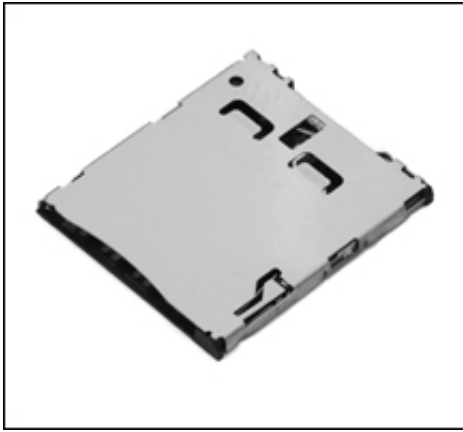




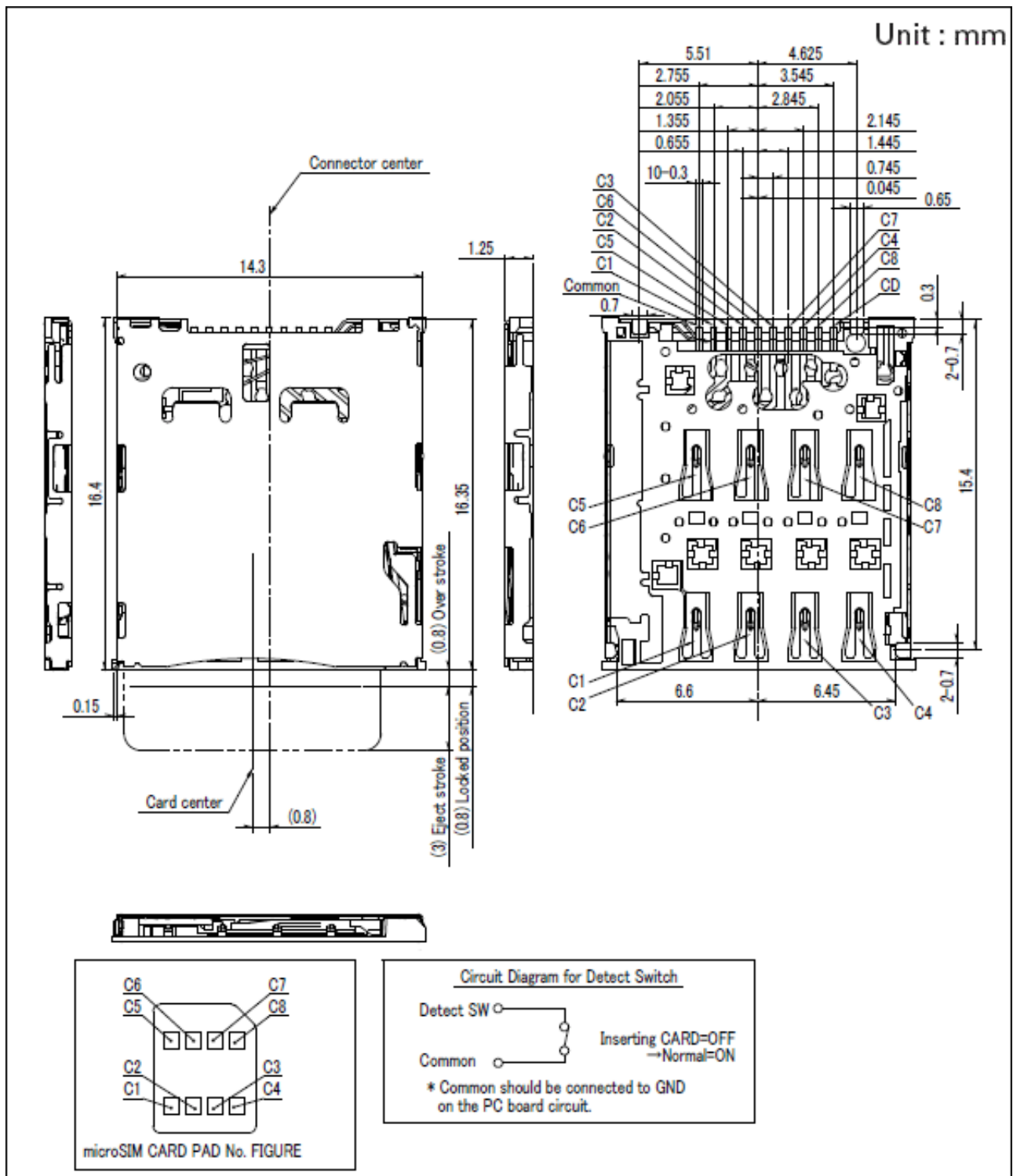
## For microSIM Card (Push-push Type) SCGD Series

Part number	<b>SCGD1B0208</b>	
Applicable media	microSIM card	
Media ejection structure	Push-push type	
Mounting type	Surface mounting type	
Mounting style	Standard mount	
Card eject stroke	3mm	
Stand-off	0mm	
Minimum order unit (pcs.)	1,600	
Operating temperature range	-25°C to +60°C	
Voltage proof	250V AC 1 minute	
Insulation resistance (Initial)	1,000MΩ min.	
Contact resistance (Initial)	Connector contacts	100mΩ max.
	Detection Switch	500mΩ max.
Insertion and removal cycle	5,000 cycles	

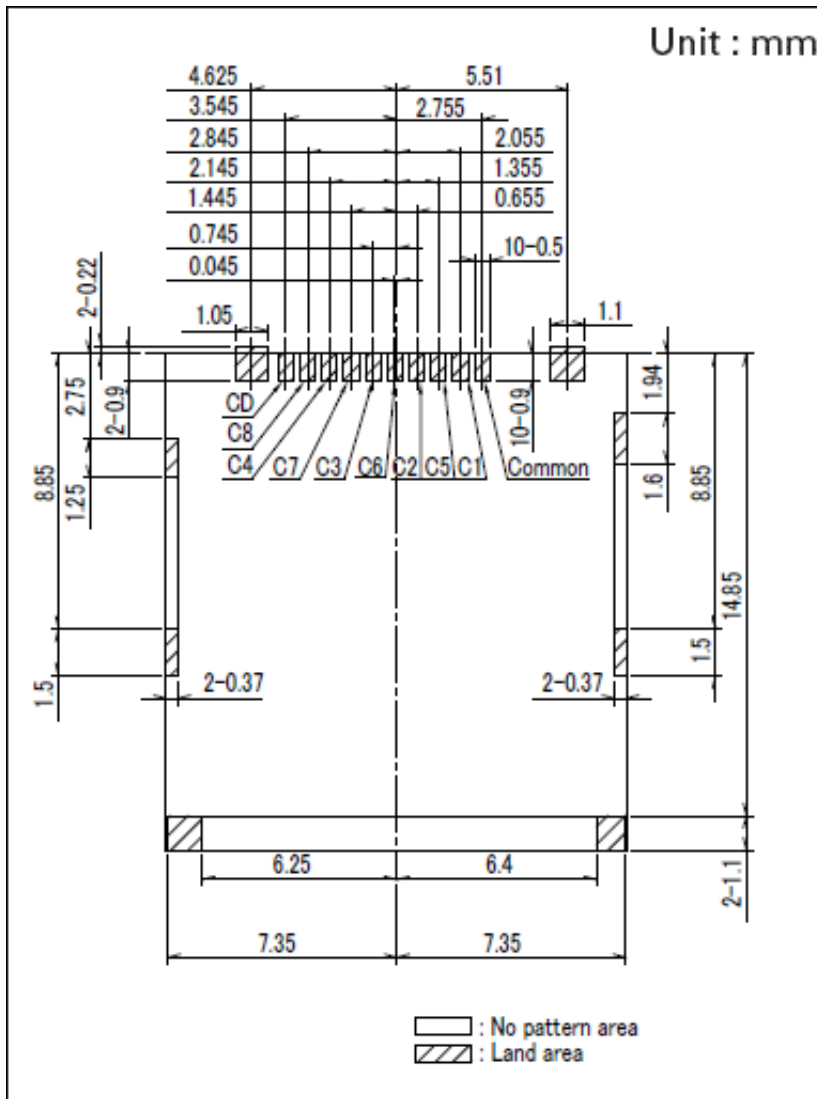
### Photo



## Dimensions

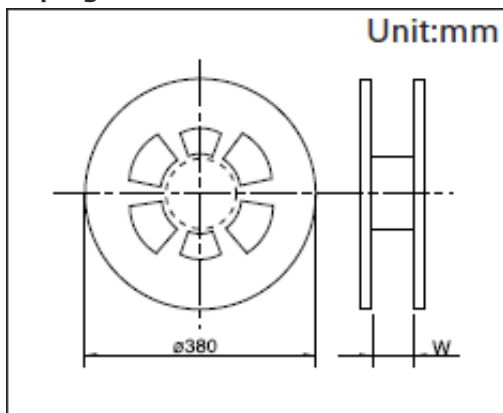


## Mounting Dimensions



### Packing Specifications

#### Taping



Number of packages 1 reel (pcs.)	1,600
1 case / Japan	4,800
1 case / export	9,600

## packing

Reel width W(mm)	57.5
Tape width (mm)	56
Export package measurements (mm)	403×403×303

## Soldering Conditions

**Example of Reflow Soldering Condition (Reference)**

## 1. Heating method

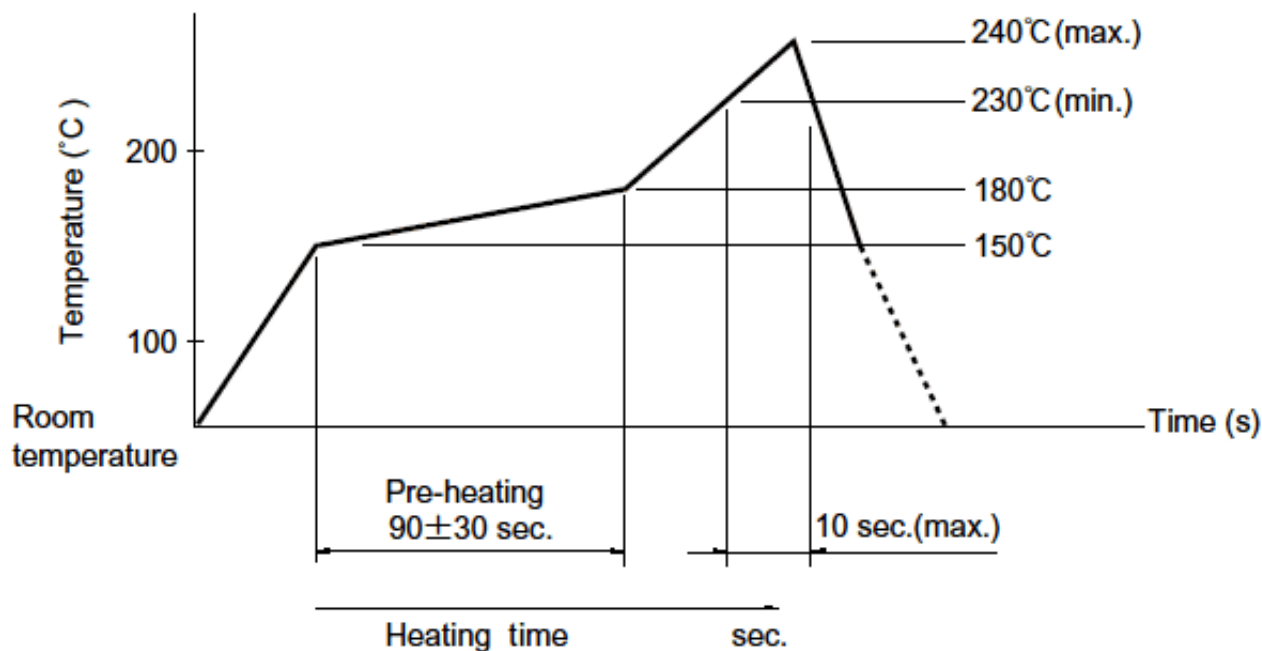
Double heating method with infrared heater.

## 2. Temperature measurement

Thermocouple 0.1 to 0.2  $\Phi$  CA (K) or CC (T) at soldering portion.

## 3. Temperature profile.

[▲ Page top](#)



## Notes are common to this series/models.

1. This site catalog shows only outline specifications. When using the products, please obtain formal specifications for supply.
2. Please place purchase orders per minimum order unit (integer).